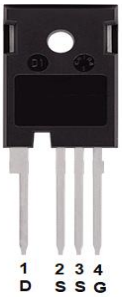
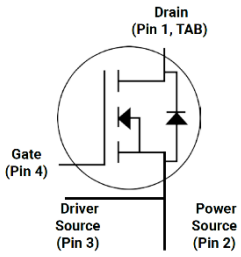
Product Summary

V_{DS} = 1200 V
I_D@25ºC = 105A
$R_{DS(ON)}$ = 18mΩ





TO-247-4

Features

- High Blocking Voltage
- High Frequency Operation
- Low on-resistance
- Fast intrinsic diode with low reverse recovery
- 100% avalanche tested

Benefits

- Higher System Efficiency
- Parallel Device Convenience without thermal runaway
- High Temperature Application
- Hard Switching & Higher Reliability
- Easy to drive

Applications

- Motor Drives
- Solar / Wind Inverters
- EV Charging Station
- AC/DC converters
- DC/DC converters
- Uninterruptable power supplies

Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DSmax}	Drain - Source Voltage		1200	V
V_{GSmax}	Gate - Source Voltage (dynamic), T_{surge} <100ns		-10 / +25	V
V_{GSop}	Gate - Source Voltage (static)		-5 / +20	V
I_D	Continuous Drain Current	V_{GS} = 20V, T_C=25°C V_{GS} = 20V, T_C=100°C	105 74	A
$I_{D(pulse)}$	Pulsed Drain Current at T_C=25°C		220	A
E_{AS}	Avalanche Energy	V_{DD} = 100V, V_{GS}=20V, L=2mH	784	mJ
I_{AV}	Avalanche Peak Current		28	A
P_D	Total power dissipation	T_C=25°C	428	W
T_J	Operating Junction Temperature		-55 to 175	°C
T_{STG}	Storage Temperature		-55 to 175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Electrical Characteristics (T_C=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 100μA	1200			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 20mA	1.9	2.45	3.8	V
		V_{DS} = V_{GS}, I_D = 20mA, T_J = 150°C		1.7		
		V_{DS} = V_{GS}, I_D = 20mA, T_J = 175°C		1.6		
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 1200V, V_{GS} = 0V	0	1	50	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS} = 20V, V_{DS} = 0V	0	1	200	nA
Gate-Source Leakage Current	I_{GSS}	V_{GS} = -5V, V_{DS} = 0V	-200	-1	0	nA
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 20V, I_D = 50 A		18	26	mΩ
		V_{GS} = 20V, I_D = 50 A, T_J = 150°C		30		
		V_{GS} = 20V, I_D = 50 A, T_J = 175°C		34		
		V_{GS} = 18V, I_D = 50 A		20		
Transconductance	g_{fs}	V_{DS} = 20V, I_D = 50 A,		39		S
		V_{DS} = 20V, I_D = 50 A, T_J = 150°C		34		
		V_{DS} = 20V, I_D = 50 A, T_J = 175°C		33		
Input capacitance	C_{iss}	V_{DS} = 1000V, V_{GS} = 0V f = 100KHz		4770		pF
Output capacitance	C_{oss}			216		
Reverse transfer capacitance	C_{rss}			16		
C_{oss} Stored Energy	E_{oss}			141		μJ
Total gate charge	Q_g	V_{DS} = 800V, V_{GS} = -5V / 20V I_D = 50 A,		239		nC
Gate-source charge	Q_{gs}			62		
Gate-drain charge	Q_{gd}			78		
Internal gate input resistance	$R_{g(int)}$	f = 1MHz, I_D = 0A		3.6		Ω
Turn-On Switching Energy	E_{ON}	V_{DS} = 800 V, V_{GS} = -5V/20V, I_D = 50A, $R_{G(ext)}$ =2Ω, L=100μH		1200		μJ
Turn-Off Switching Energy	E_{OFF}			150		
Turn-On Delay Time	$t_{d(on)}$			24		ns
Rise Time	t_r			25		
Turn-Off Delay Time	$t_{d(off)}$			58		
Fall Time	t_f			15		

Reverse Diode Characteristics (T_C=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Diode Forward Voltage	V_{SD}	V_{GS} = -5V, I_{SD} = 25A,		4.3		V
		V_{GS} = -5V, I_{SD} = 25A, T_J = 150°C		3.9		
		V_{GS} = -5V, I_{SD} = 25A, T_J = 175°C		3.8		
Continuous Diode Forward Current	I_S	V_{GS} = -5V			91	A
Reverse Recovery time	t_{rr}	V_{GS} = -5V, I_{SD} = 50A, V_R= 800V, dif/dt = 3600 A/μs		21		ns
Reverse Recovery Charge	Q_{rr}			475		nC
Peak Reverse Recovery Current	I_{rrm}			40		A

Thermal Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Thermal Resistance (per device)	$R_{th(j-c)}$	junction-case		0.27	0.35	^{0}C/W

Typical Performance

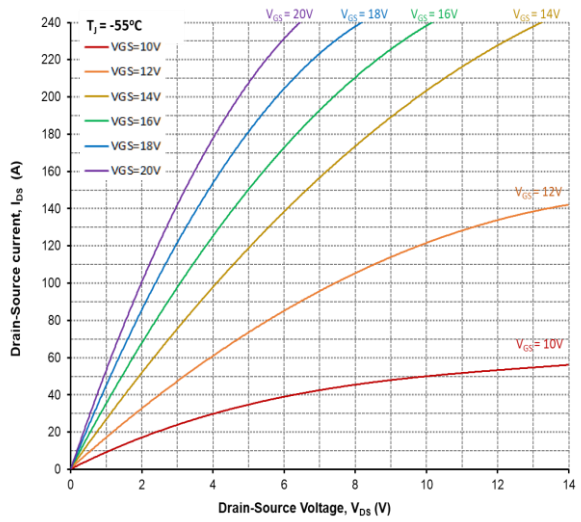


Figure 1. Output Characteristics, T_J = -55ºC

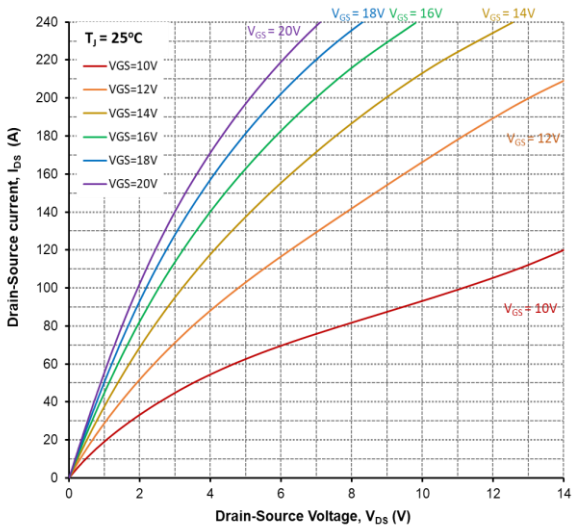


Figure 2. Output Characteristics, T_J = 25ºC

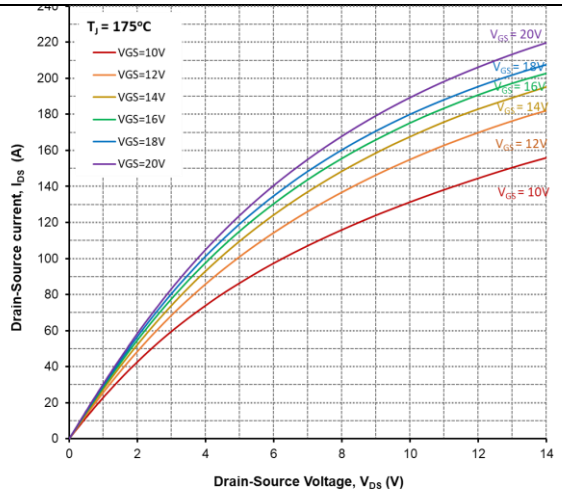


Figure 3. Output Characteristics, T_J = 175ºC

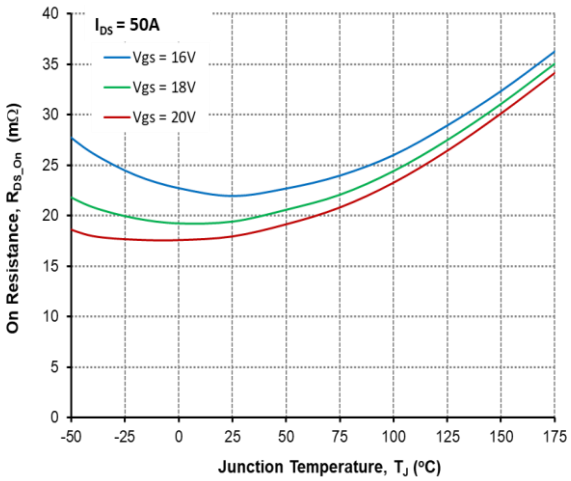


Figure 4. On-Resistance vs. Temperature

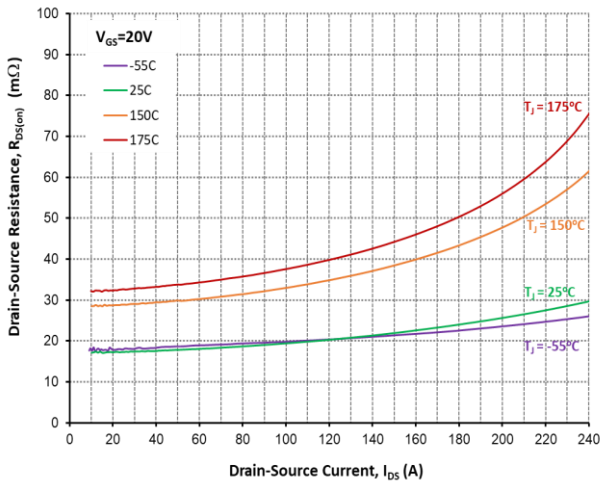


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

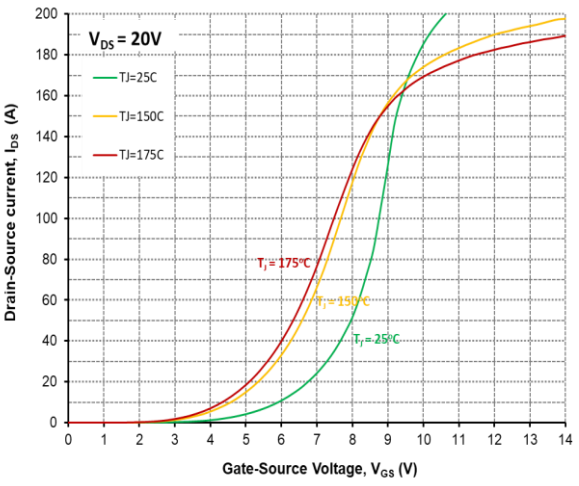


Figure 6. Transfer Characteristic For Various Junction Temperatures

Typical Performance

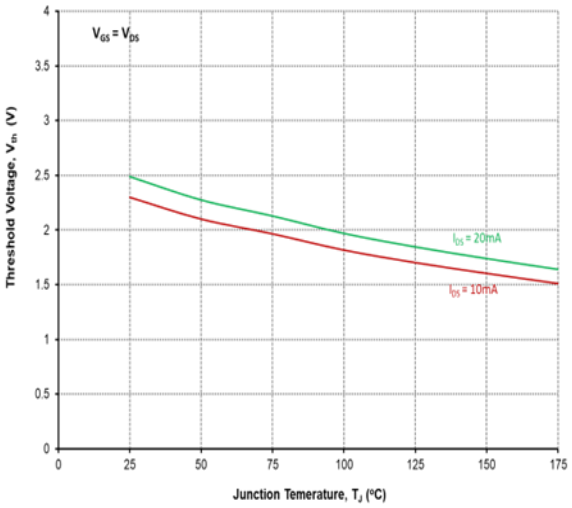


Figure 7. Threshold Voltage vs. Temperature

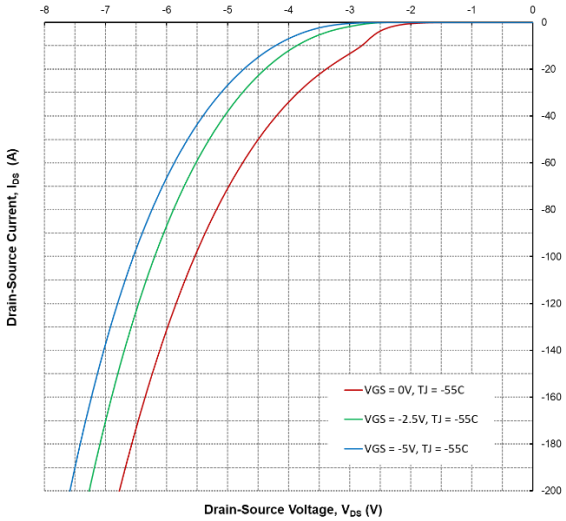


Figure 8. Body Diode Characteristics @ -55°C

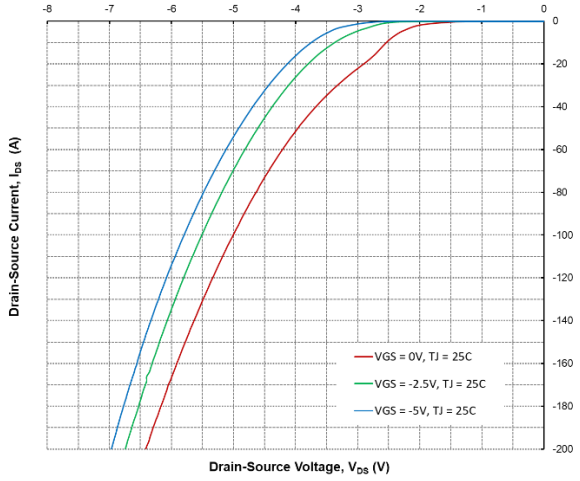


Figure 9. Body Diode Characteristics @ 25°C

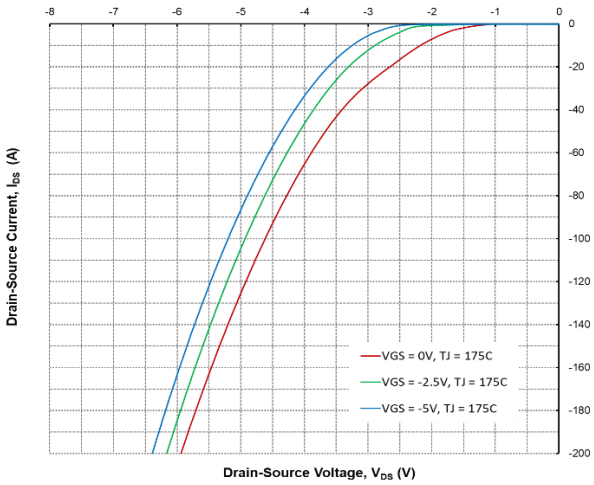


Figure 10. Body Diode Characteristics @ 175°C

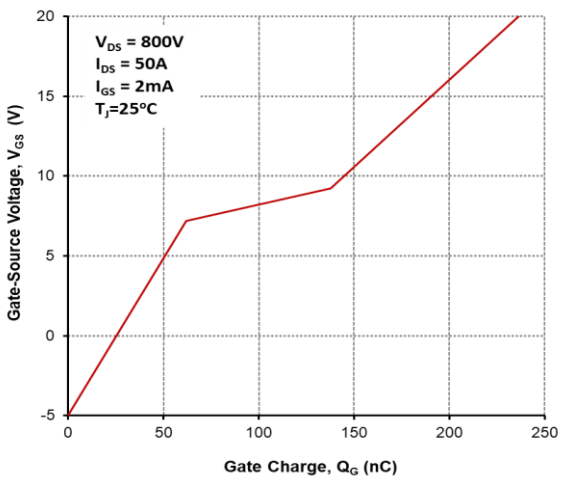


Figure 11. Gate Charge Characteristics

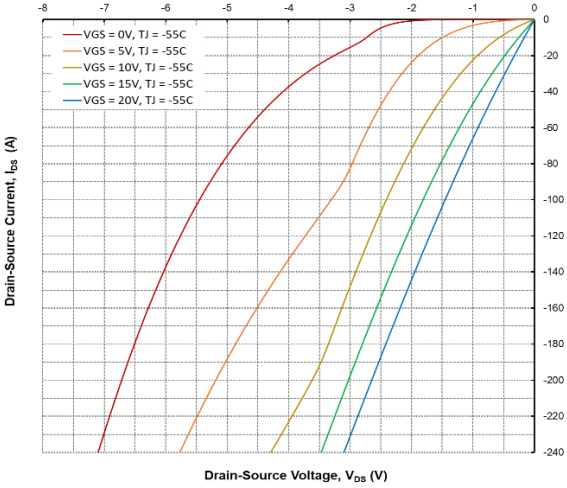


Figure 12. 3rd Quadrant Characteristics @ -55°C

Typical Performance

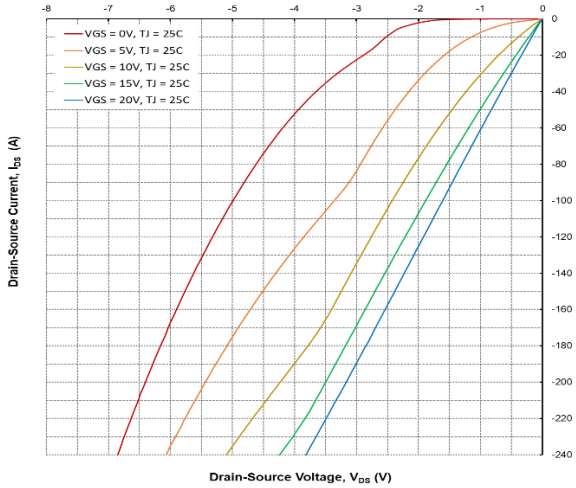


Figure 13. 3rd Quadrant Characteristics @ 25ºC

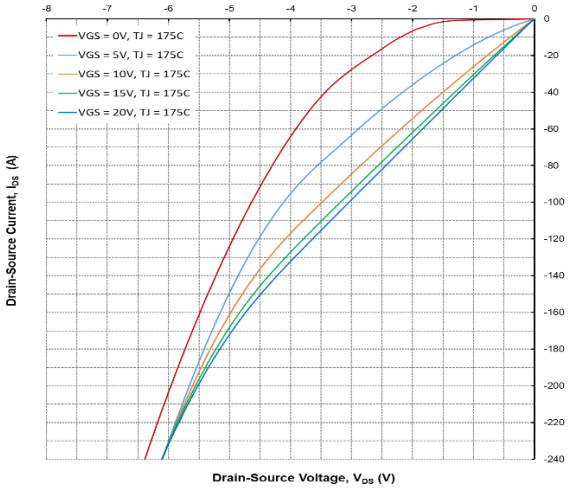


Figure 14. 3rd Quadrant Characteristics @ 175ºC

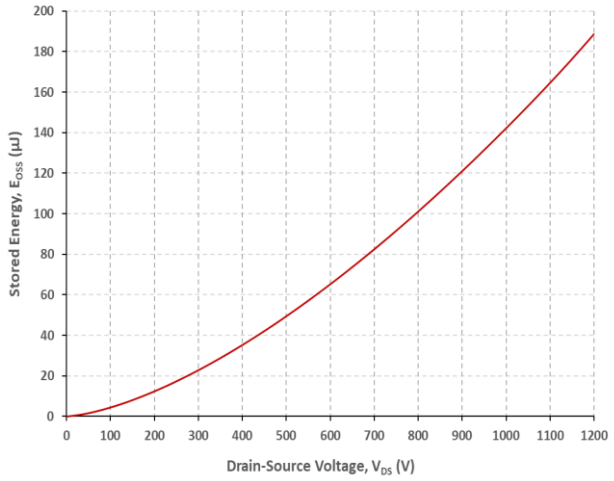


Figure 15. Output Capacitor Stored Energy

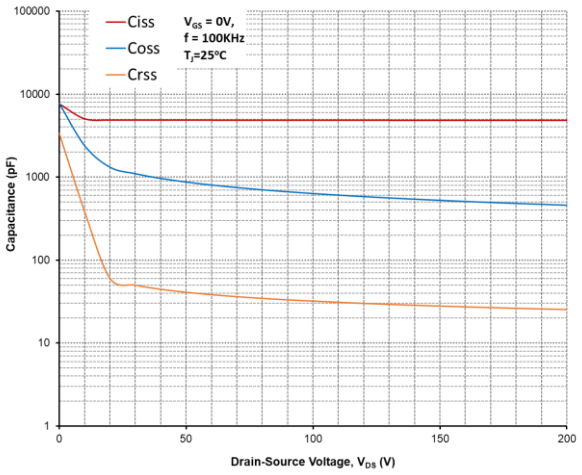


Figure 16. Capacitances vs. Drain-Source Voltage (0-200V)

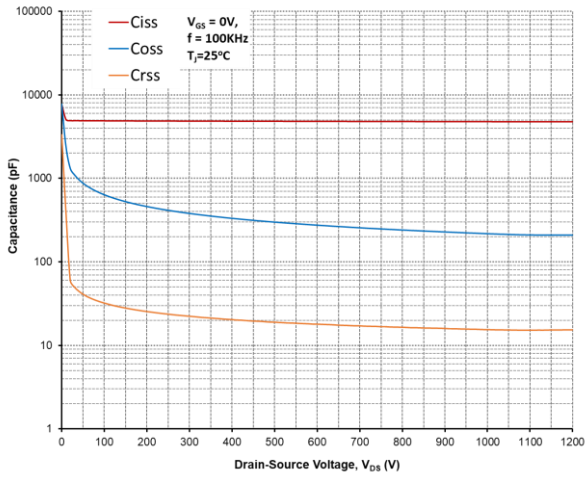


Figure 17. Capacitances vs. Drain-Source Voltage (0-1200V)

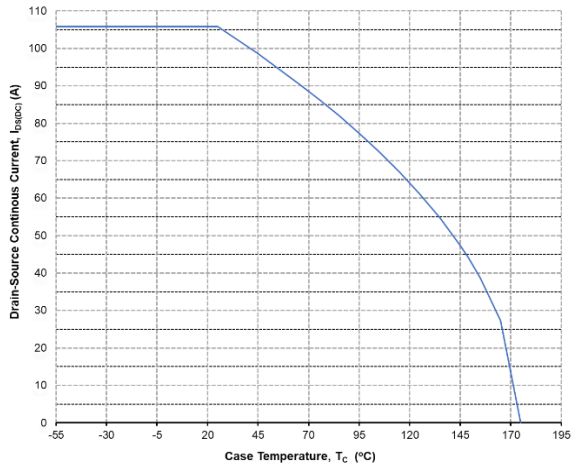


Figure 18. Continuous Drain Current Derating vs. Case Temperature

Typical Performance

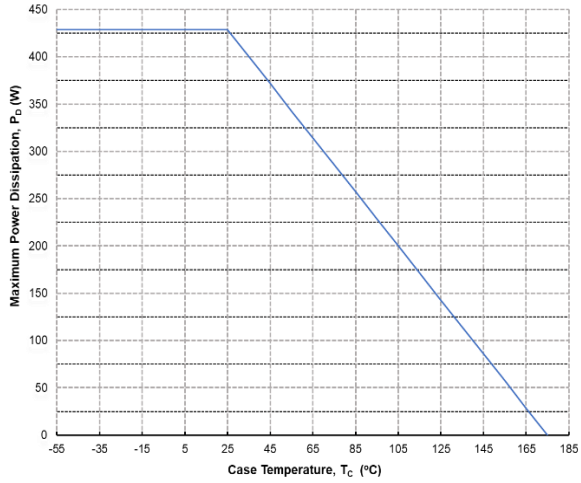


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

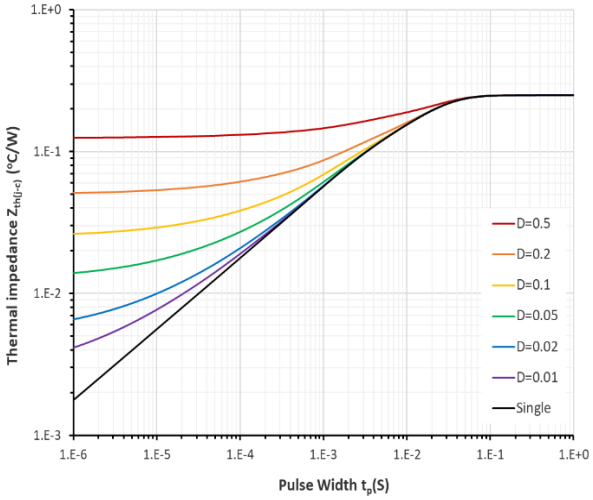


Figure 20. Transient Thermal Impedance (Junction to Case)

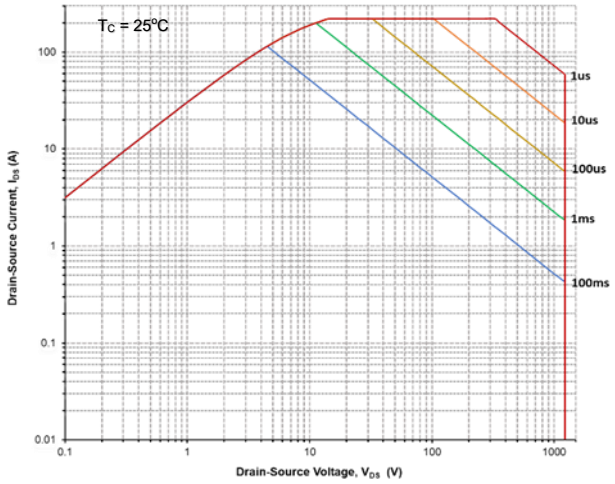


Figure 21. Safe Operating Area

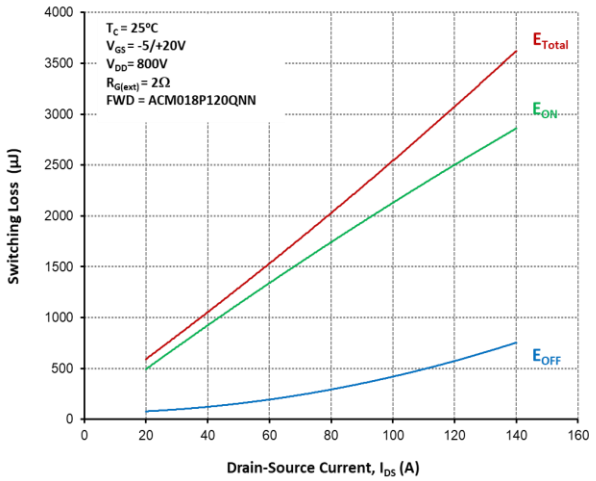


Figure 22. Switching energy vs Drain current

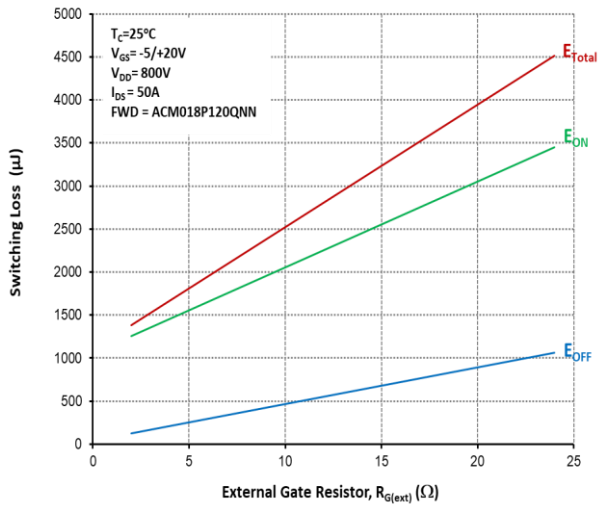


Figure 23. Switching energy vs External Gate Resistor

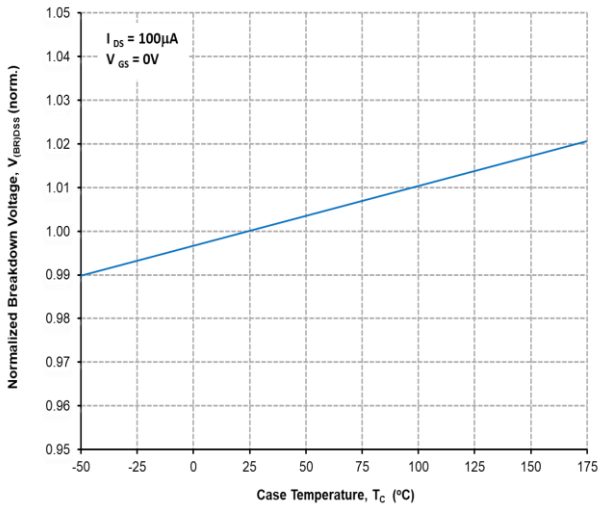
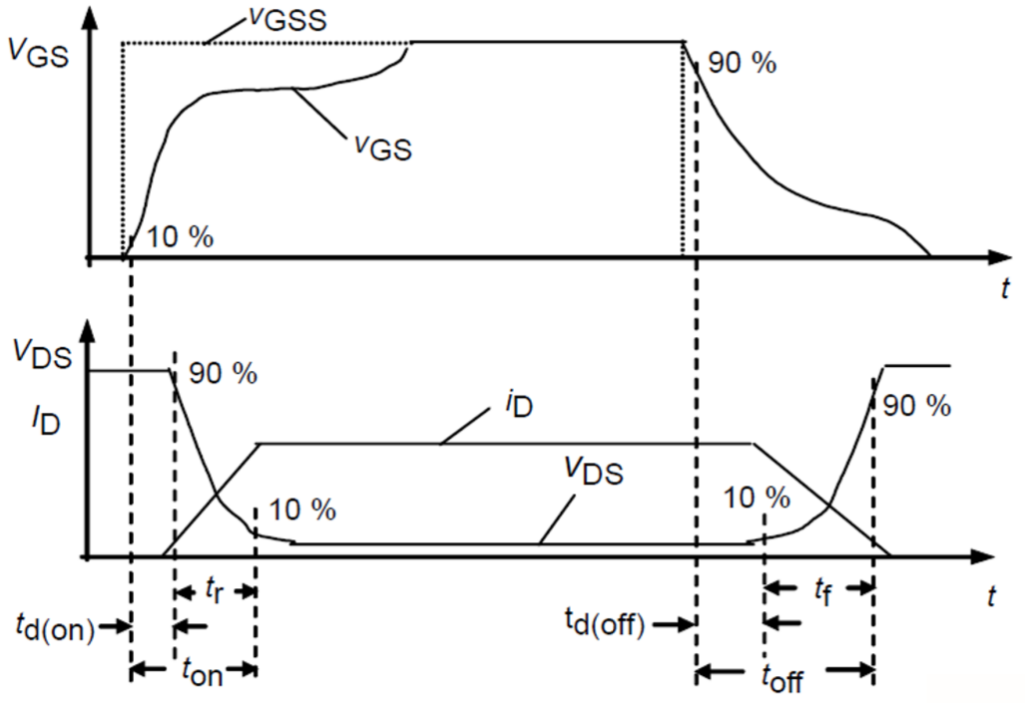
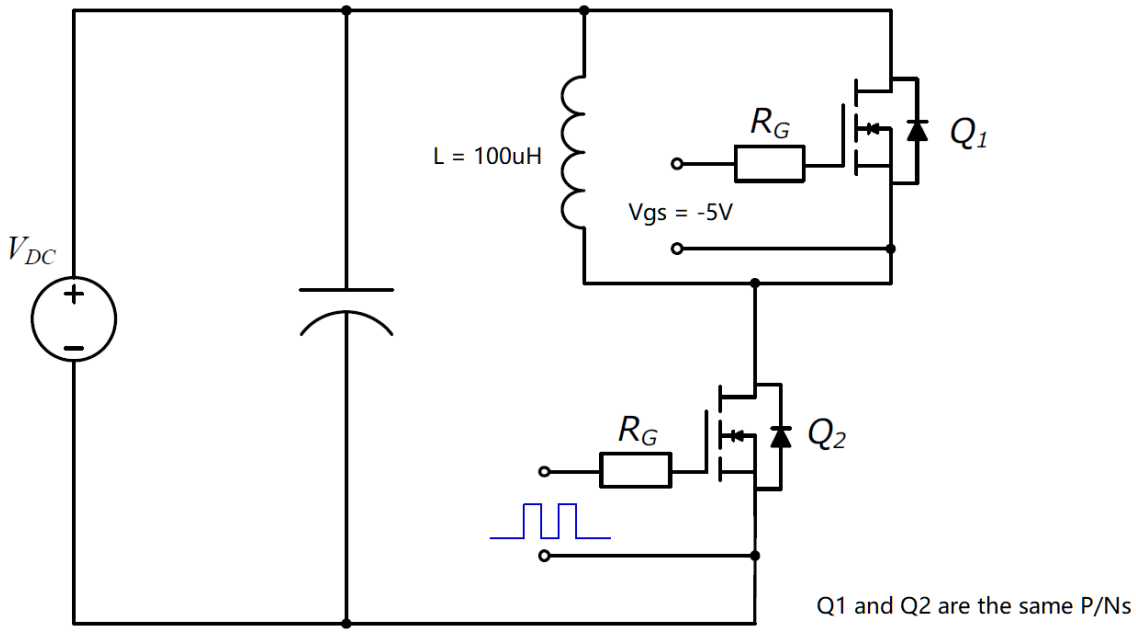


Figure 24. Normalized breakdown voltage vs Temperature

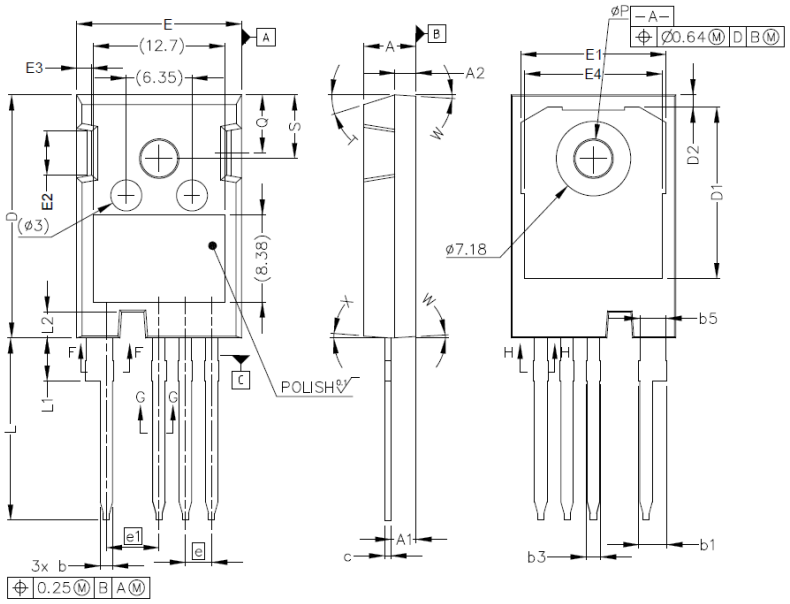
Switching Times Definition and Test Circuit

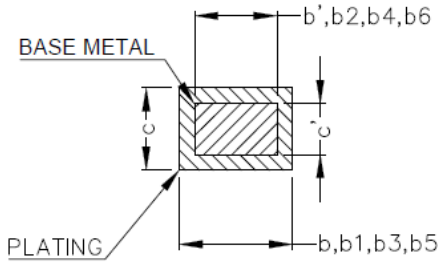




Package Dimensions

(TO-247-4 Package)





SECTION "F-F", "G-G" AND "H-H"
SCALE: NONE

SYMBOL	MILLIMETERS	
	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	2.39	2.94
b2	2.39	2.84
b3	1.07	1.60
b4	1.07	1.50
b5	2.39	2.69
b6	2.39	2.64
c'	0.55	0.65
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	2.54 BSC	
e1	5.08 BSC	
N	4	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
øP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5 ° REF.	
X	4° REF.	

NOTE ;
1. ALL METAL SURFACES: TIN PLATED,EXCEPT AREA OF CUT
2. DIMENSIONING & TOLERANCEING CONFIRM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.